



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model [List multiple models if applicable.]

HP 7503 Switch Chassis(JD240C)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers	0
Components, parts and materials containing radioactive substances	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

3.1.1 Guidance of treatments to the product:

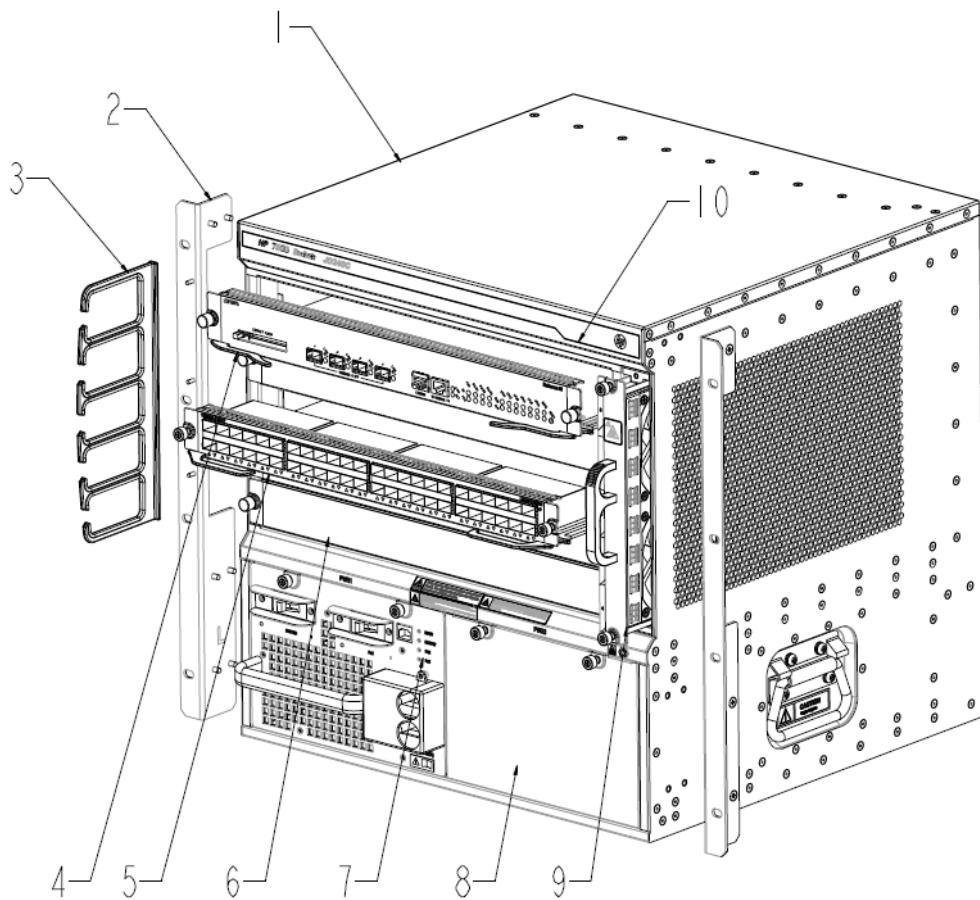


Figure 1 Front of HP 7503

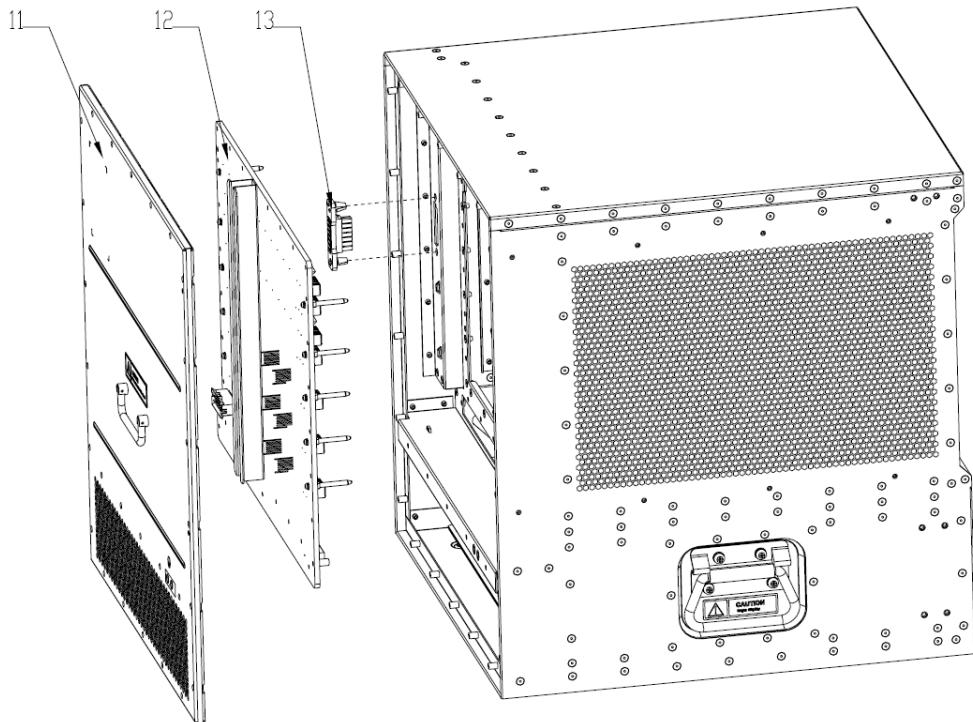


Figure 2 Rear of HP 7503

1. Unscrew the screws on mounting angle 2, and then remove mounting angle 2;
2. Unscrew the screws on cabling rack 3, and then remove cabling rack 3 from mounting angle 2;
3. Unscrew the screws on front panel 4, and then remove front panel 4;
4. Unscrew the screws on front panel 5, and then remove front panel 5;
5. Unscrew the screws on filler panel 6, and then remove filler panel 6. The others should be removed in the same way;
6. Unscrew the screws on power supply module 7, and then remove power supply module 7;
7. Unscrew the screws on filler panel 8, and then remove filler panel 8;
8. Unscrew the screws on fan module frame 9, and then remove fan module frame 9;
9. Remove film 10;
10. Unscrew the screws on rear cover plate 11, and then remove rear cover plate 11;
11. Remove all of the inner cables;
12. Unscrew the screws on PCB 12, and then remove PCB 12;
13. Remove plug 13;
14. Remove all of the labels;
15. Remove all of shielding fingers.

3.1.2 Guidance of treatments to module 4:

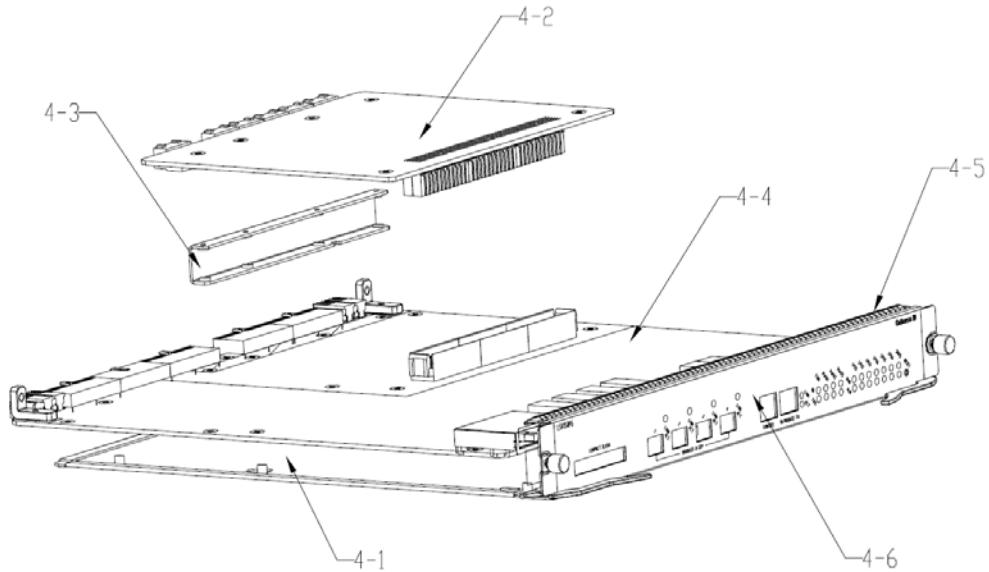


Figure 3 Treatments to module 4

1. Unscrew the screws on PCB 4-2, and then remove PCB 4-2;
2. Unscrew the screws on PCB support plate 4-3, and then remove PCB support plate 4-3;
3. Unscrew the screws on PCB 4-4, and then remove PCB 4-4;
4. Remove shielding finger 4-5 from front panel 4-1;
5. Remove film 4-6 from front panel 4-1.

3.1.3 Guidance of treatments to module 5:

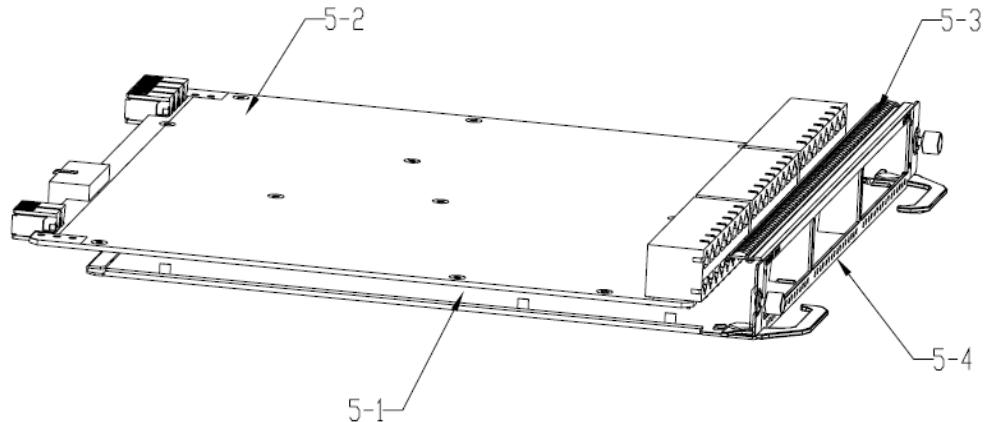


Figure 4 Treatments to module 5

1. Unscrew the screws on PCB 5-2, and then remove PCB 5-2;
2. Remove shielding finger 5-3 from front panel 5-1;
3. Remove film 5-4 from front panel 5-1;

3.1.4 Guidance of treatments to blank panel 6:

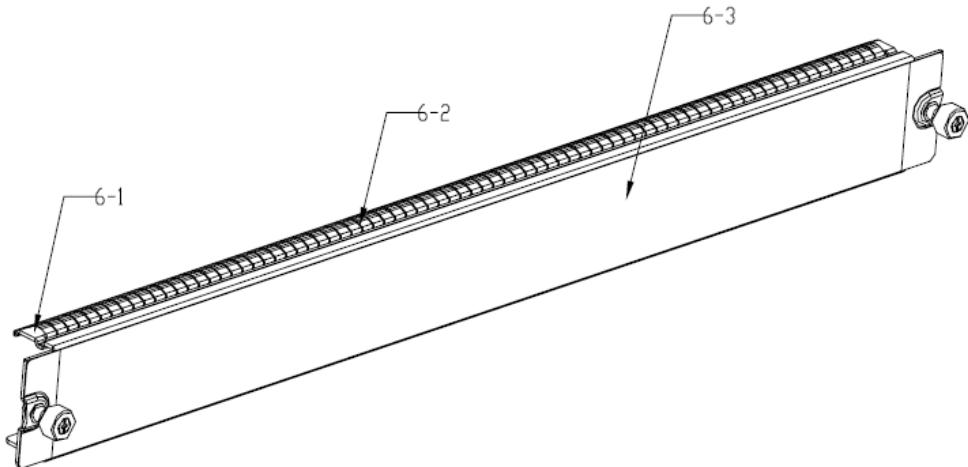


Figure 5 Treatments to blank panel 6

1. Remove shielding finger 6-2 from blank panel 6-1;
2. Remove film 6-3 from blank panel 6-1;

3.1.7 Guidance of treatments to fan module frame 9

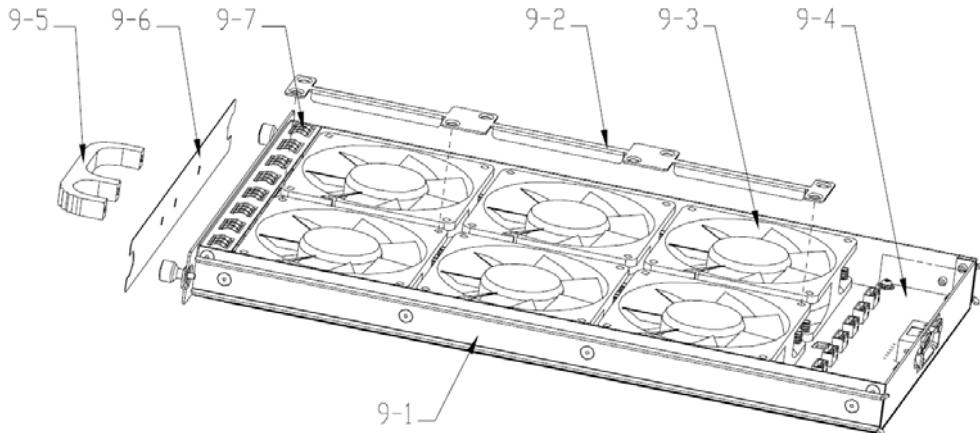


Figure 6 Treatments to fan module frame 9

1. Unscrew the screws on cover plate 9-2, and then remove cover plate 9-2;
2. Remove the six fans 9-3 from fan frame 9-1;
3. Unscrew the screws on PCB 9-4, and then remove PCB 9-4;
4. Remove all of the inner cables;
5. Unscrew the screws on handle 9-5, and then remove handle 9-5;
6. Remove film 9-6 from fan frame 9-1;
7. Remove shielding finger 9-7 from fan frame 9-1.

3.2 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percent age	Selective treatment for materials and components	Details
1		Fe	20967	49.03%		Fe recycling
2		Fe	852	1.99%		Fe recycling
3		ABS	37	0.09%		
4						
	4-1	Fe	1566	3.66%		Fe recycling
	4-2	Complex PWB	528	1.23%	The surface of PCB is greater than 10 square centimeters	
	4-3	Fe		2.34%		Fe recycling
	4-4	Complex PWB	1000	3.48%	The surface of PCB is greater than 10 square centimeters	
5						
	5-1	Fe	1487	3.48%		Fe recycling
	5-2	Complex PWB	1000	2.34%	The surface of PCB is greater than 10 square centimeters	
6						
	6-1	Fe	303*2	1.42%		Fe recycling
7		Complex PWB+Fe	8021	18.76%	1. Containing brominated flame retardants ; 2. The surface of PCB is greater than 10 square centimeters; 3. Electrolyte capacitor height	Fe recycling
8		Fe	524	1.23%		Fe recycling
9						
	9-1	Fe	799	1.87%		Fe recycling
	9-2	Fe	40	0.09%		Fe recycling
	9-3	Pla	98*6	1.37%		Pla recycling
	9-4	Complex PWB	95	0.22%	The surface of PCB is greater than 10 square centimeters	
11		Fe	2083	4.87%		Fe recycling
12		Complex PWB	1673	3.91%	The surface of PCB is greater than 10 square centimeters	
cables	04043396 0404A05T 04042967 0404A07K	Cu, Pla	899	2.10%	1. Containing brominated flame retardants 2. 04043396 is external cables	Cu、Pla recycling

4. Revised record

Date	Version	Author	Modify content
2015.06.26	V0	Xu Jianbin	Initial version